

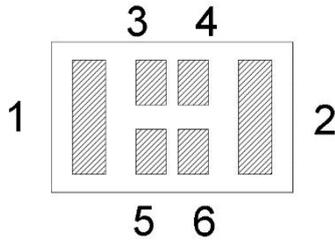
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

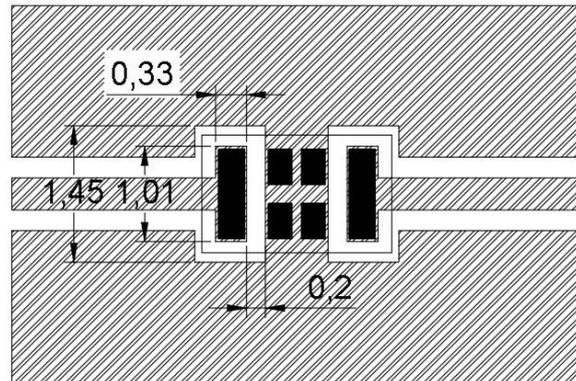
NO.	Parameter	Frequency (MHz)	SPC		
			Min.	Typ.	Max.
1	Insertion Loss (dB)	3300~4200			2.1
2	VSWR	3300~4200			2.1
3	Attenuation (dB)	100~915	43		
		1427~1467	43		
		1627~1661	45		
		1695~1785	40		
		1850~2025	40		
		2300~2400	35		
		2400~2495	35		
		2496~2690	28		
		2700~3050	1		
		4450~4900	4		
		4900~5925	33		
		6600~8400	33		
		9900~12600	33		
4	In/Output Impedance ( $\Omega$ )		50		
5	Permissible Input Power (W)		1		
<b>Operating &amp; Storage Condition (Component)</b>					
Operation Temperature Range: -40°C ~ +85°C					
Storage Temperature Range: -40°C ~ +85°C					
<b>Storage Condition before Soldering (Included packaging material)</b>					
Storage Temperature Range: +5 ~ +40 °C					
Humidity: 30 to 70% relative humidity					

### Construction



PIN	Connection
1	Input port
2	Output port
3,4,5,6	GND

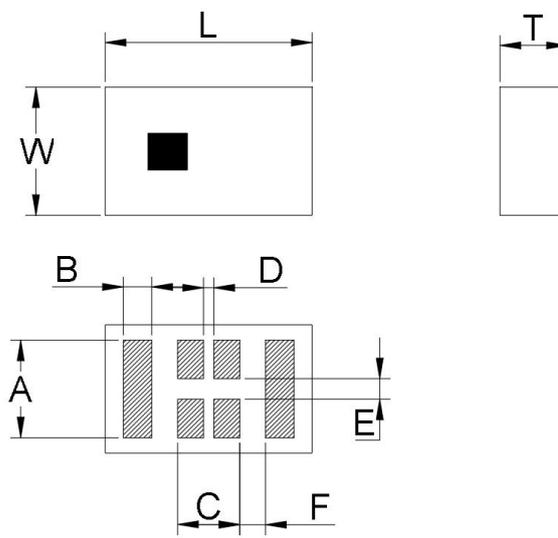
### Mounting Considerations



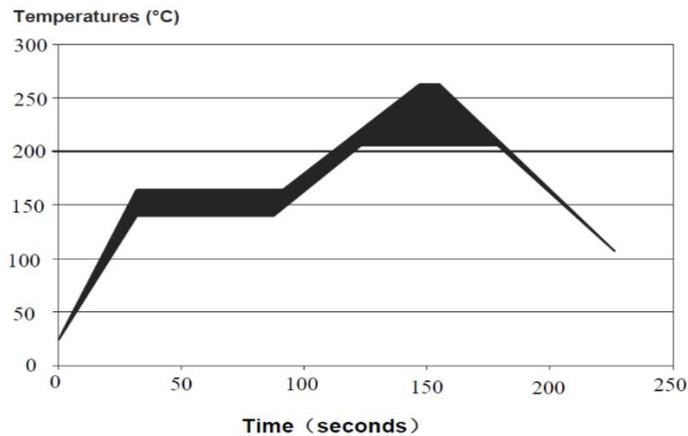
Unit: mm

Line width to be designed to match 50  $\Omega$  characteristic impedance, depending on PCB material and thickness

### Dimensions

Figure	Symbol	Dimension (mm)
	L	2.00±0.20
	W	1.25±0.20
	T	0.65±0.10
	A	0.95±0.10
	B	0.28±0.10
	C	0.60±0.10
	D	0.10±0.10
	E	0.20±0.10
F	0.25±0.10	

### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.